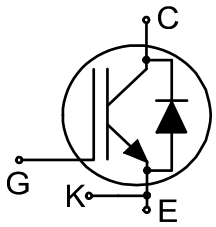
TRENCHSTOP™ 5 soft switching IGBT

TRENCHSTOP™ 5 high speed soft switching IGBT copacked with full current rated RAPID 1 fast and soft antiparallel diode

Features and Benefits:



High speed S5 technology offering
- High speed smooth switching device for hard & soft switching
- Very Low V_{CEsat}, 1.42V at nominal current
- Plug and play replacement of previous generation IGBTs
- 650V breakdown voltage
- Low gate charge Q_G
- IGBT copacked with full rated RAPID 1 fast antiparallel diode
- Maximum junction temperature 175°C
- Qualified according to JEDEC for target applications
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models: http://www.infineon.com/igbt/



Applications:

- Industrial UPS
- Industrial SMPS
- Energy Storage
- Charger
- Welding

Product Validation:

Qualified for applications listed above based on the test conditions in the relevant tests of JEDEC20/22

Package pin definition:

- Pin C & backside - collector
- Pin E - emitter
- Pin K - Kelvin emitter
- Pin G - gate

Please note: The emitter and Kelvin emitter pins are not exchangeable. Their exchange might lead to malfunction.

Pb Green

Halogen-Free

RoHS

Key Performance and Package Parameters

Type	V_{CE}	I_C	V_{CEsat}, T_{vj}=25°C	T_{vjmax}	Marking	Package
IKZ50N65ES5	650V	50A	1.35V	175°C	K50EES5	PG-TO247-4

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TRENCHSTOP™ 5 soft switching IGBT

Maximum Ratings

For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.

Parameter	Symbol	Value	Unit
Collector-emitter voltage, $T_{vj} \geq 25°C$	V_{CE}	650	V
DC collector current, limited by T_{vjmax} [1)] T_C = 25°C value limited by bondwire T_C = 100°C	I_C	80.0 60.5	A
Pulsed collector current, t_p limited by T_{vjmax}	I_{Cpuls}	200.0	A
Turn off safe operating area $V_{CE} \leq 650V$, $T_{vj} \leq 175°C$, t_p = 1µs	-	200.0	A
Diode forward current, limited by T_{vjmax} [1)] T_C = 25°C value limited by bondwire T_C = 100°C	I_F	80.0 60.5	A
Diode pulsed current, t_p limited by T_{vjmax}	I_{Fpuls}	200.0	A
Gate-emitter voltage Transient Gate-emitter voltage ($t_p \leq 10µs$, $D < 0.010$)	V_{GE}	±20 ±30	V
Power dissipation T_C = 25°C Power dissipation T_C = 100°C	P_{tot}	274.0 137.0	W
Operating junction temperature	T_{vj}	-40...+175	°C
Storage temperature	T_{stg}	-55...+150	°C
Soldering temperature, wave soldering 1.6mm (0.063in.) from case for 10s		260	°C
Mounting torque, M3 screw Maximum of mounting processes: 3	M	0.6	Nm

Thermal Resistance

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
R_{th} Characteristics						
IGBT thermal resistance, junction - case	$R_{th(j-C)}$		-	-	0.55	K/W
Diode thermal resistance, junction - case	$R_{th(j-C)}$		-	-	0.63	K/W
Thermal resistance junction - ambient	$R_{th(j-a)}$		-	-	40	K/W

[1)] value limited by bondwire

Electrical Characteristic, at T_{vj} = 25°C, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Static Characteristic						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	V_{GE} = 0V, I_C = 0.20mA	650	-	-	V
Collector-emitter saturation voltage	V_{CEsat}	V_{GE} = 15.0V, I_C = 50.0A T_{vj} = 25°C T_{vj} = 125°C T_{vj} = 175°C	 - - -	 1.35 1.50 1.60	 1.70 - -	V
Diode forward voltage	V_F	V_{GE} = 0V, I_F = 50.0A T_{vj} = 25°C T_{vj} = 125°C T_{vj} = 175°C	 - - -	 1.45 1.42 1.39	 1.70 - -	V
Gate-emitter threshold voltage	$V_{GE(th)}$	I_C = 0.50mA, V_{CE} = V_{GE}	3.2	4.0	4.8	V
Zero gate voltage collector current	I_{CES}	V_{CE} = 650V, V_{GE} = 0V T_{vj} = 25°C T_{vj} = 175°C	 - -	 - 2000	 50 -	µA
Gate-emitter leakage current	I_{GES}	V_{CE} = 0V, V_{GE} = 20V	-	-	100	nA
Transconductance	g_{fs}	V_{CE} = 20V, I_C = 50.0A	-	62.0	-	S

Electrical Characteristic, at T_{vj} = 25°C, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Dynamic Characteristic						
Input capacitance	C_{ies}	V_{CE} = 25V, V_{GE} = 0V, f = 1MHz	-	3100	-	pF
Output capacitance	C_{oes}		-	88	-	
Reverse transfer capacitance	C_{res}		-	12	-	
Gate charge	Q_G	V_{CC} = 520V, I_C = 50.0A, V_{GE} = 15V	-	120.0	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	L_E		-	13.0	-	nH

Switching Characteristic, Inductive Load

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic, at T_{vj} = 25°C						
Turn-on delay time	$t_{d(on)}$	T_{vj} = 25°C, V_{CC} = 400V, I_C = 50.0A, V_{GE} = 0.0/15.0V, $R_{G(on)}$ = 23.1Ω, $R_{G(off)}$ = 23.1Ω, $L\sigma$ = 30nH, $C\sigma$ = 30pF $L\sigma$, $C\sigma$ from Fig. E Energy losses include “tail” and diode reverse recovery.	-	36	-	ns
Rise time	t_r		-	22	-	ns
Turn-off delay time	$t_{d(off)}$		-	294	-	ns
Fall time	t_f		-	32	-	ns
Turn-on energy	E_{on}		-	0.77	-	mJ
Turn-off energy	E_{off}		-	0.88	-	mJ
Total switching energy	E_{ts}		-	1.65	-	mJ

Turn-on delay time	$t_{d(on)}$	T_{vj} = 25°C, V_{CC} = 400V, I_C = 25.0A, V_{GE} = 0.0/15.0V, $R_{G(on)}$ = 23.1Ω, $R_{G(off)}$ = 23.1Ω, Lσ = 30nH, Cσ = 30pF Lσ, Cσ from Fig. E Energy losses include “tail” and diode reverse recovery.	-	33	-	ns
Rise time	t_r		-	14	-	ns
Turn-off delay time	$t_{d(off)}$		-	304	-	ns
Fall time	t_f		-	33	-	ns
Turn-on energy	E_{on}		-	0.36	-	mJ
Turn-off energy	E_{off}		-	0.32	-	mJ
Total switching energy	E_{ts}		-	0.68	-	mJ

Diode Characteristic, at T_{vj} = 25°C

Diode reverse recovery time	t_{rr}	T_{vj} = 25°C, V_R = 400V, I_F = 50.0A, di_F/dt = 2500A/µs	-	62	-	ns
Diode reverse recovery charge	Q_{rr}		-	1.40	-	µC
Diode peak reverse recovery current	I_{rrm}		-	40.0	-	A
Diode peak rate of fall of reverse recovery current during t_b	di_{rr}/dt		-	-1100	-	A/µs

Diode reverse recovery time	t_{rr}	T_{vj} = 25°C, V_R = 400V, I_F = 25.0A, di_F/dt = 2500A/µs	-	44	-	ns
Diode reverse recovery charge	Q_{rr}		-	1.00	-	µC
Diode peak reverse recovery current	I_{rrm}		-	38.5	-	A
Diode peak rate of fall of reverse recovery current during t_b	di_{rr}/dt		-	-2200	-	A/µs

Switching Characteristic, Inductive Load

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic, at T_{vj} = 150°C						
Turn-on delay time	$t_{d(on)}$	T_{vj} = 150°C, V_{CC} = 400V, I_C = 50.0A, V_{GE} = 0.0/15.0V, $R_{G(on)}$ = 23.1Ω, $R_{G(off)}$ = 23.1Ω, Lσ = 30nH, Cσ = 30pF Lσ, Cσ from Fig. E Energy losses include “tail” and diode reverse recovery.	-	34	-	ns
Rise time	t_r		-	26	-	ns
Turn-off delay time	$t_{d(off)}$		-	328	-	ns
Fall time	t_f		-	38	-	ns
Turn-on energy	E_{on}		-	1.00	-	mJ
Turn-off energy	E_{off}		-	1.20	-	mJ
Total switching energy	E_{ts}		-	2.20	-	mJ

Turn-on delay time	$t_{d(on)}$	T_{vj} = 150°C, V_{CC} = 400V, I_C = 25.0A, V_{GE} = 0.0/15.0V, $R_{G(on)}$ = 23.1Ω, $R_{G(off)}$ = 23.1Ω, Lσ = 30nH, Cσ = 30pF Lσ, Cσ from Fig. E Energy losses include “tail” and diode reverse recovery.	-	32	-	ns
Rise time	t_r		-	16	-	ns
Turn-off delay time	$t_{d(off)}$		-	354	-	ns
Fall time	t_f		-	44	-	ns
Turn-on energy	E_{on}		-	0.64	-	mJ
Turn-off energy	E_{off}		-	0.56	-	mJ
Total switching energy	E_{ts}		-	1.20	-	mJ

Diode Characteristic, at T_{vj} = 150°C

Diode reverse recovery time	t_{rr}	T_{vj} = 150°C, V_R = 400V, I_F = 50.0A, di_F/dt = 2500A/µs	-	92	-	ns
Diode reverse recovery charge	Q_{rr}		-	3.20	-	µC
Diode peak reverse recovery current	I_{rrm}		-	63.0	-	A
Diode peak rate of fall of reverse recovery current during t_b	di_{rr}/dt		-	-1100	-	A/µs

Diode reverse recovery time	t_{rr}	T_{vj} = 150°C, V_R = 400V, I_F = 25.0A, di_F/dt = 2500A/µs	-	68	-	ns
Diode reverse recovery charge	Q_{rr}		-	2.30	-	µC
Diode peak reverse recovery current	I_{rrm}		-	59.0	-	A
Diode peak rate of fall of reverse recovery current during t_b	di_{rr}/dt		-	-1850	-	A/µs

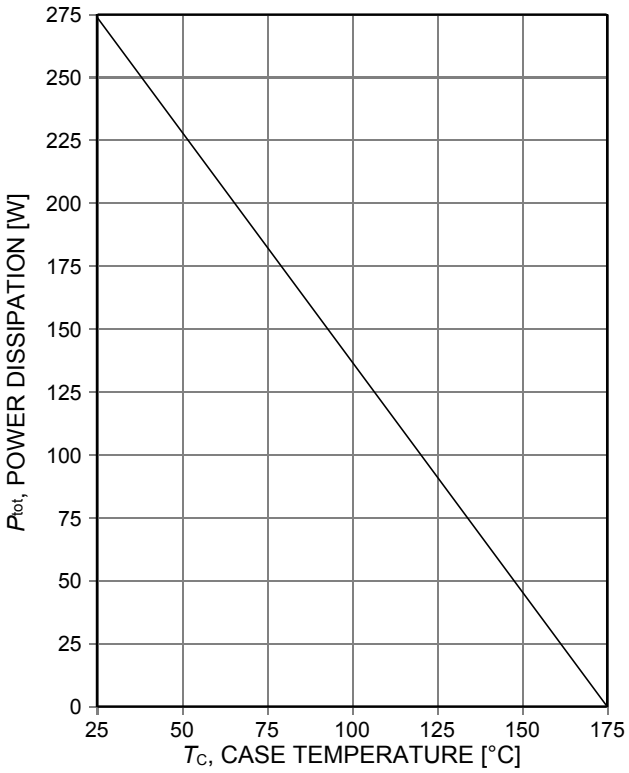


Figure 1. **Power dissipation as a function of case temperature**
(T_{vj}≤175°C)

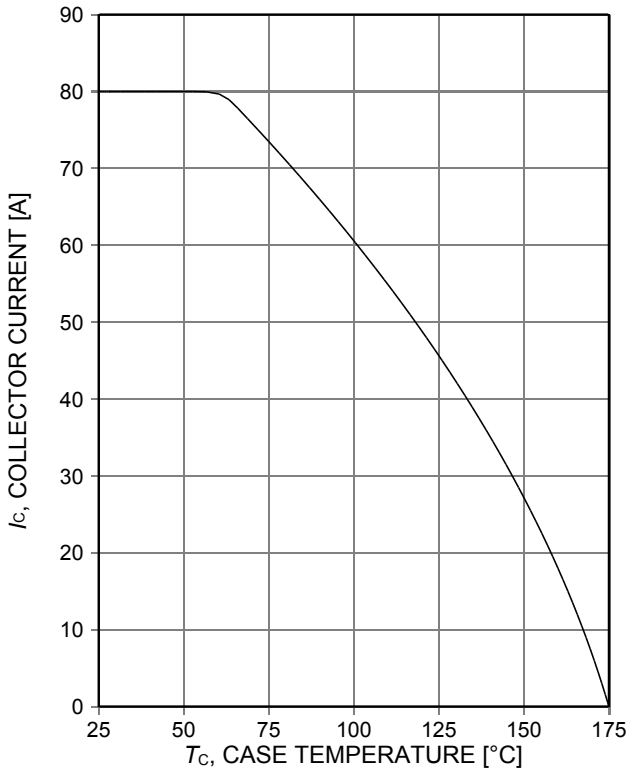


Figure 2. **Collector current as a function of case temperature**
(V_{GE}≥15V, T_{vj}≤175°C)

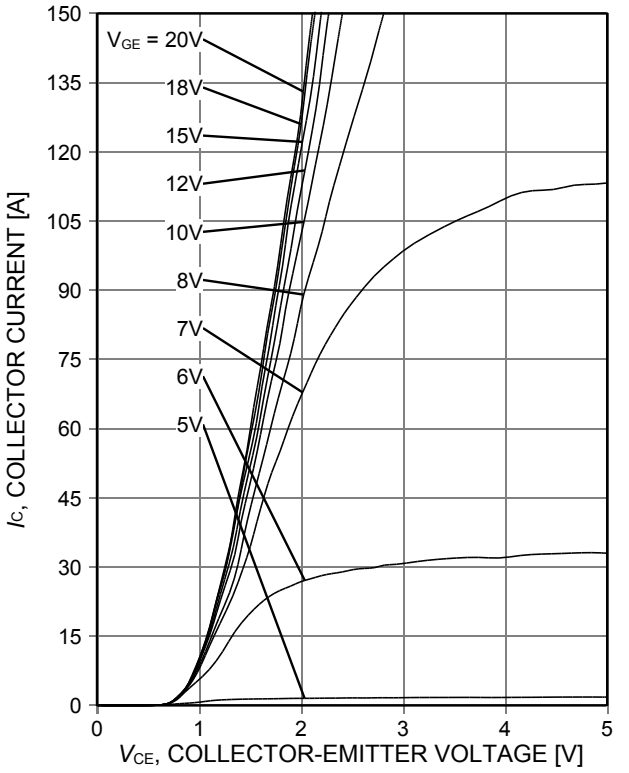


Figure 3. **Typical output characteristic**
(T_{vj}=25°C)

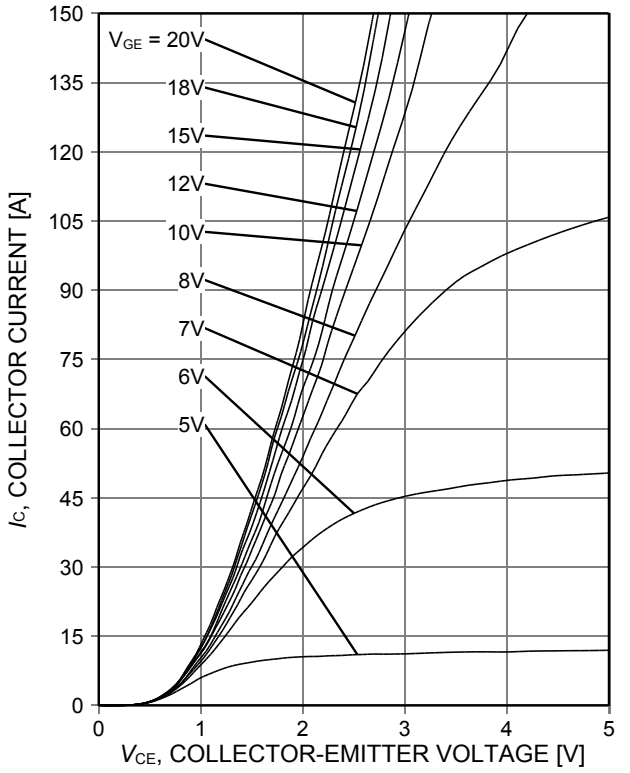


Figure 4. **Typical output characteristic**
(T_{vj}=175°C)

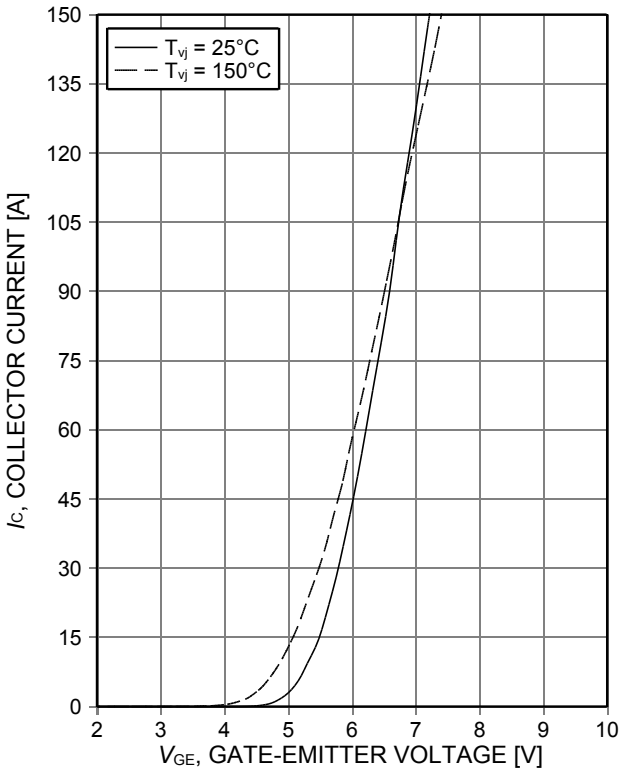


Figure 5. **Typical transfer characteristic**
(V_{CE}=20V)

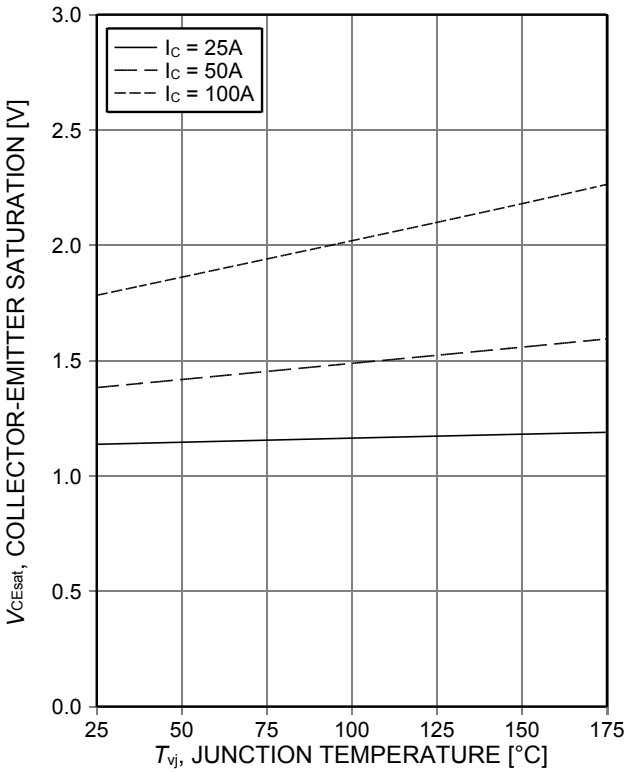


Figure 6. **Typical collector-emitter saturation voltage as a function of junction temperature**
(V_{GE}=15V)

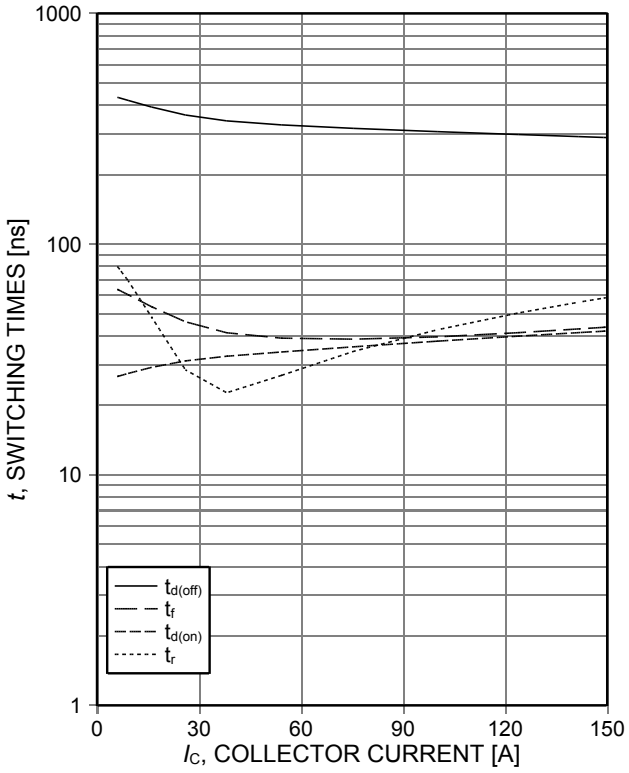


Figure 7. **Typical switching times as a function of collector current**
(inductive load, T_{vj}=150°C, V_{CE}=400V, V_{GE}=0/15V, R_{Gon}=23,1Ω, R_{Goff}=23,1Ω, dynamic test circuit in Figure E)

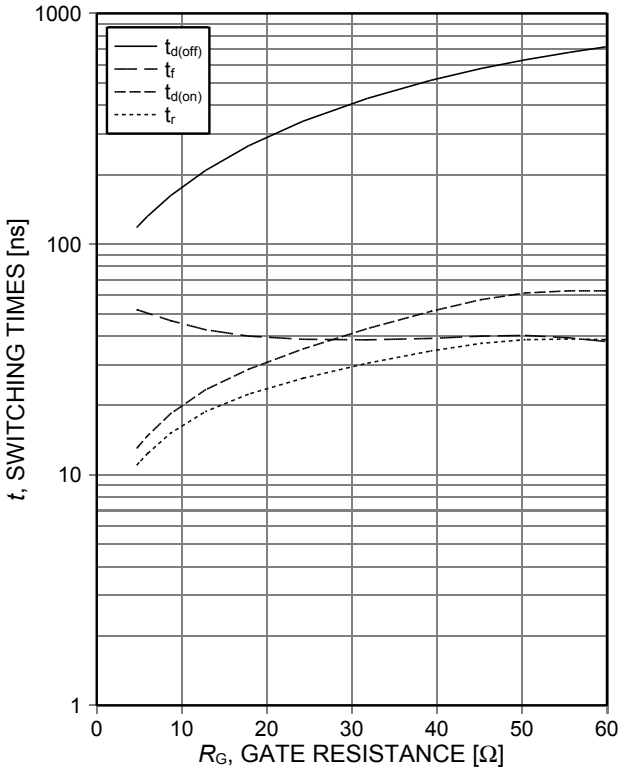


Figure 8. **Typical switching times as a function of gate resistance**
(inductive load, T_{vj}=150°C, V_{CE}=400V, V_{GE}=0/15V, I_C=75A, dynamic test circuit in Figure E)

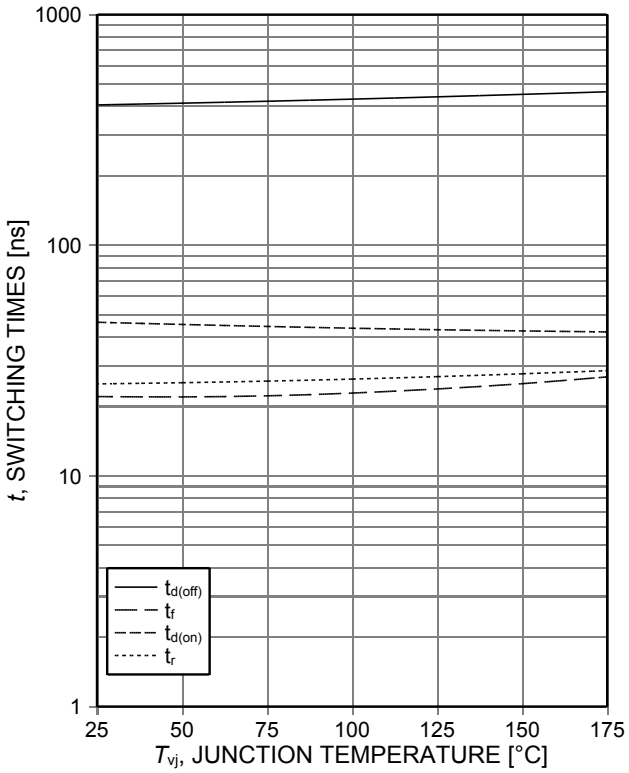


Figure 9. **Typical switching times as a function of junction temperature**
(inductive load, V_{CE}=400V, V_{GE}=0/15V, I_C=75A, R_{Gon}=23,1Ω, R_{Goff}=23,1Ω, dynamic test circuit in Figure E)

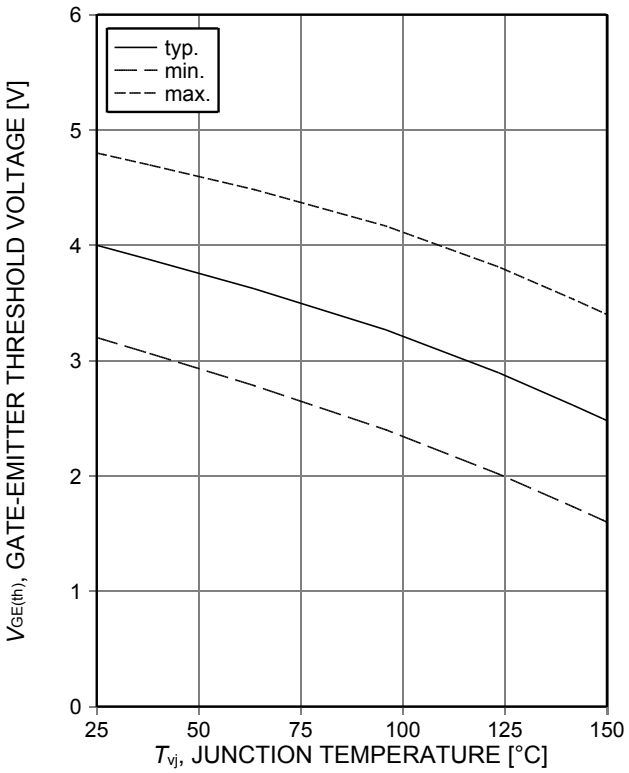


Figure 10. **Gate-emitter threshold voltage as a function of junction temperature**
(I_C=0.5mA)

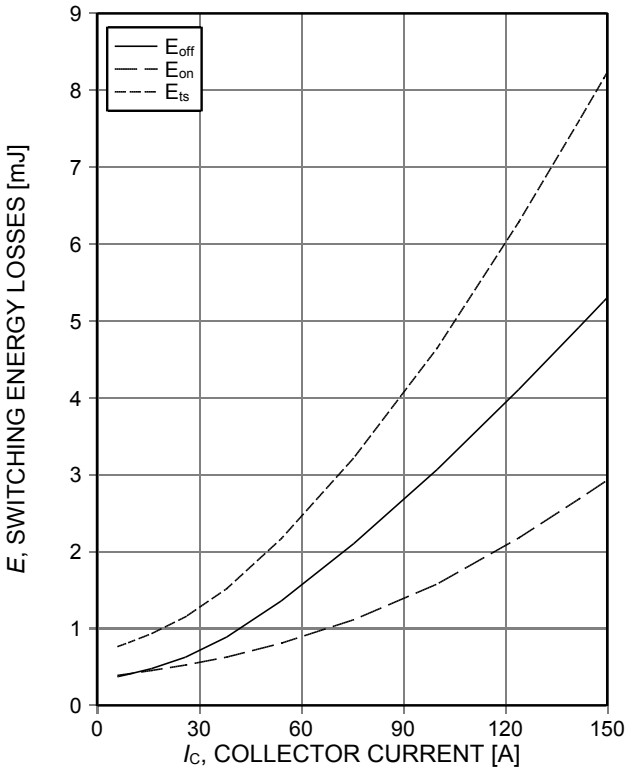


Figure 11. **Typical switching energy losses as a function of collector current**
(inductive load, T_{vj}=150°C, V_{CE}=400V, V_{GE}=0/15V, R_{Gon}=23,1Ω, R_{Goff}=23,1Ω, dynamic test circuit in Figure E)

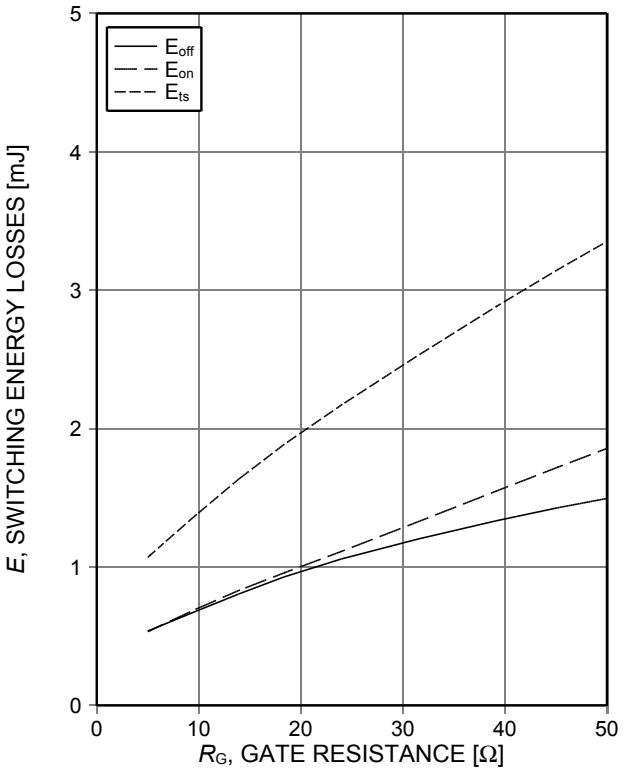


Figure 12. **Typical switching energy losses as a function of gate resistance**
(inductive load, T_{vj}=150°C, V_{CE}=400V, V_{GE}=0/15V, I_C=75A, dynamic test circuit in Figure E)

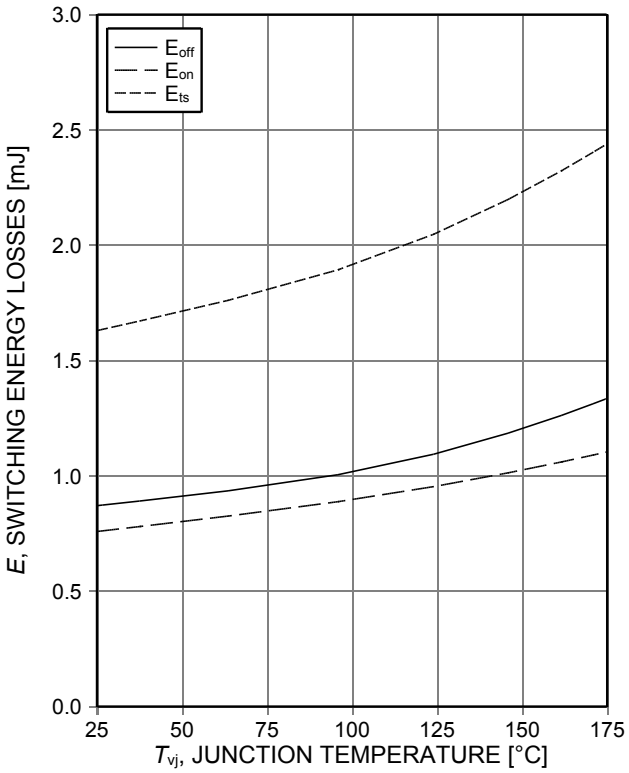


Figure 13. **Typical switching energy losses as a function of junction temperature** (inductive load, V_{CE}=400V, V_{GE}=0/15V, I_C=75A, R_{Gon}=23,1Ω, R_{Goff}=23,1Ω, dynamic test circuit in Figure E)

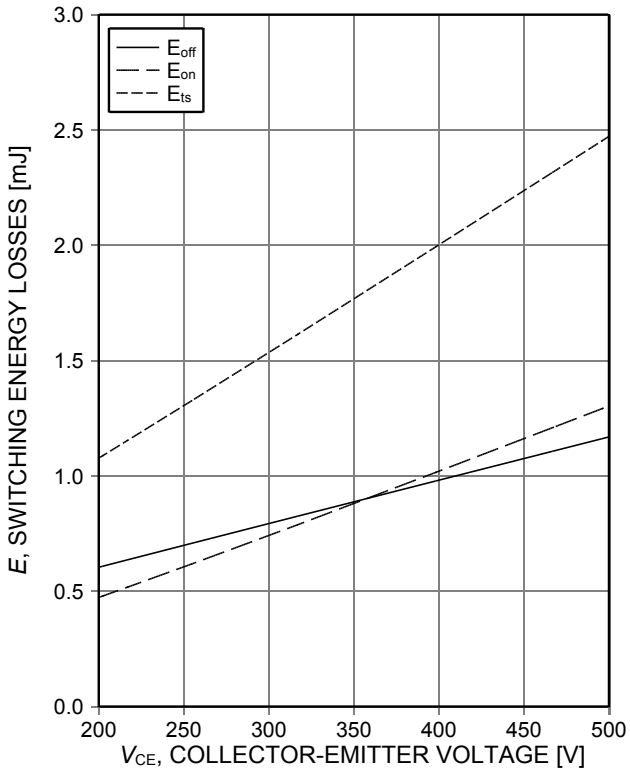


Figure 14. **Typical switching energy losses as a function of collector emitter voltage** (inductive load, T_{vj}=150°C, V_{GE}=0/15V, I_C=75A, R_{Gon}=23,1Ω, R_{Goff}=23,1Ω, dynamic test circuit in Figure E)

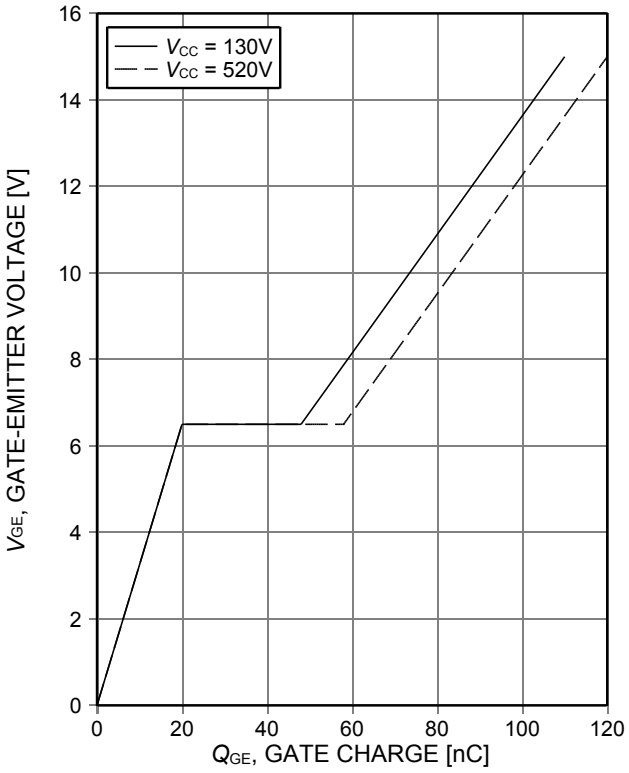


Figure 15. **Typical gate charge** (I_C=75A)

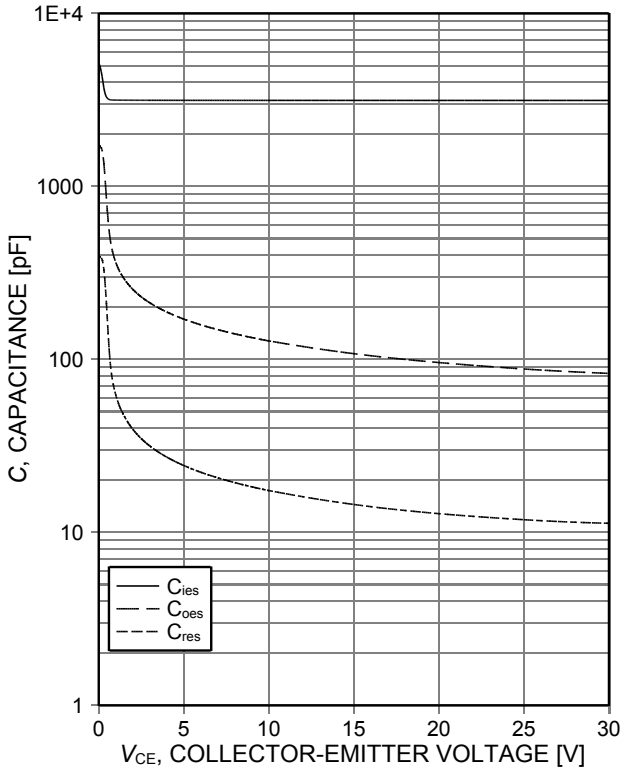


Figure 16. **Typical capacitance as a function of collector-emitter voltage** (V_{GE}=0V, f=1MHz)

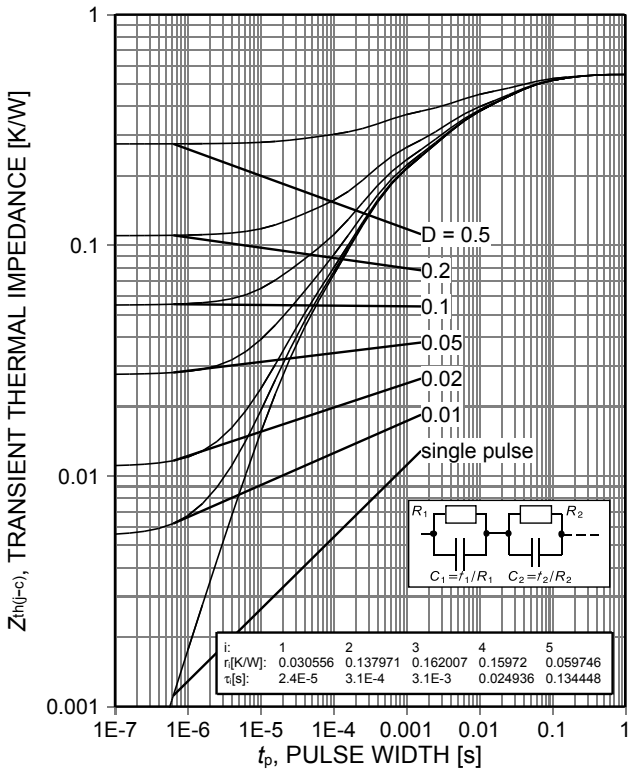


Figure 17. **IGBT transient thermal impedance** ($D=t_p/T$)

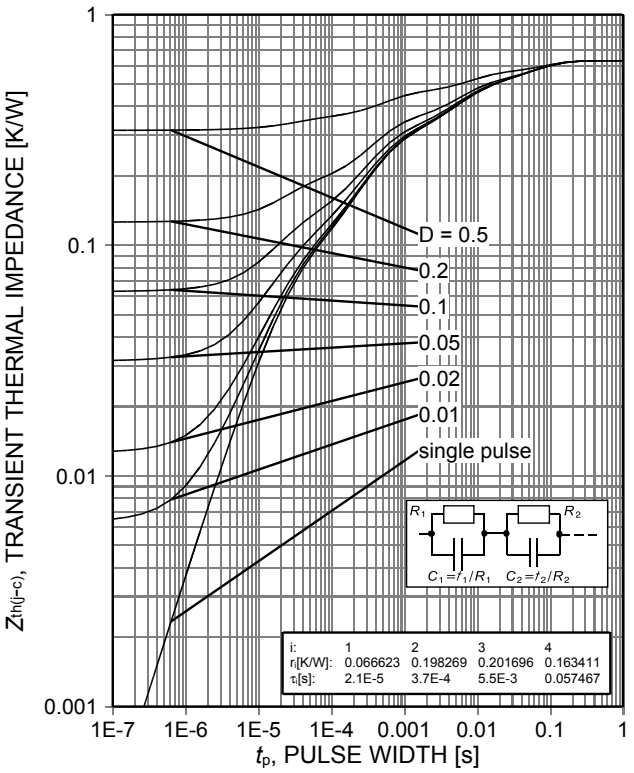


Figure 18. **Diode transient thermal impedance as a function of pulse width** ($D=t_p/T$)

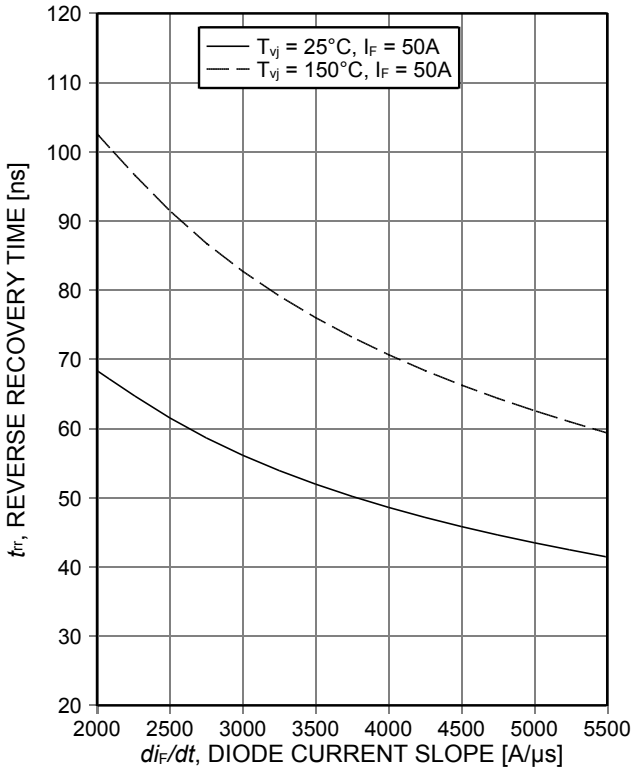


Figure 19. **Typical reverse recovery time as a function of diode current slope** (V_R=400V)

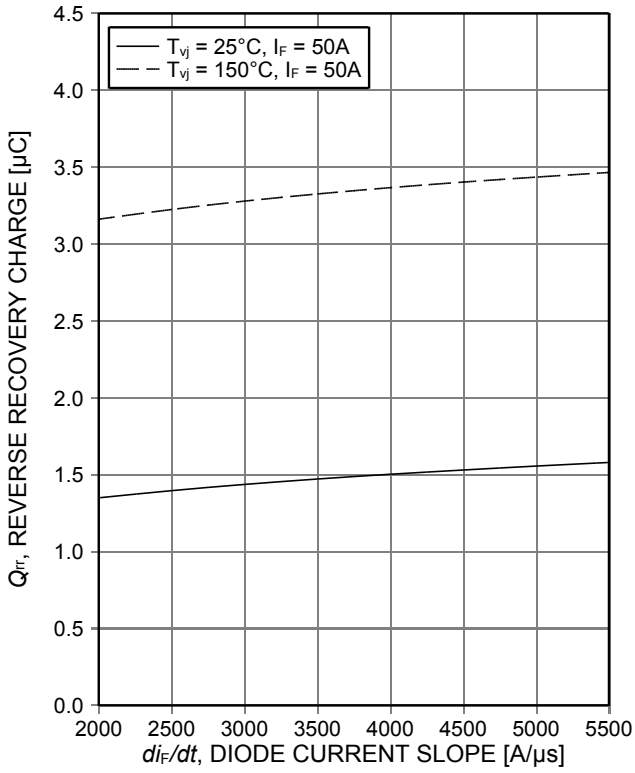


Figure 20. **Typical reverse recovery charge as a function of diode current slope** (V_R=400V)

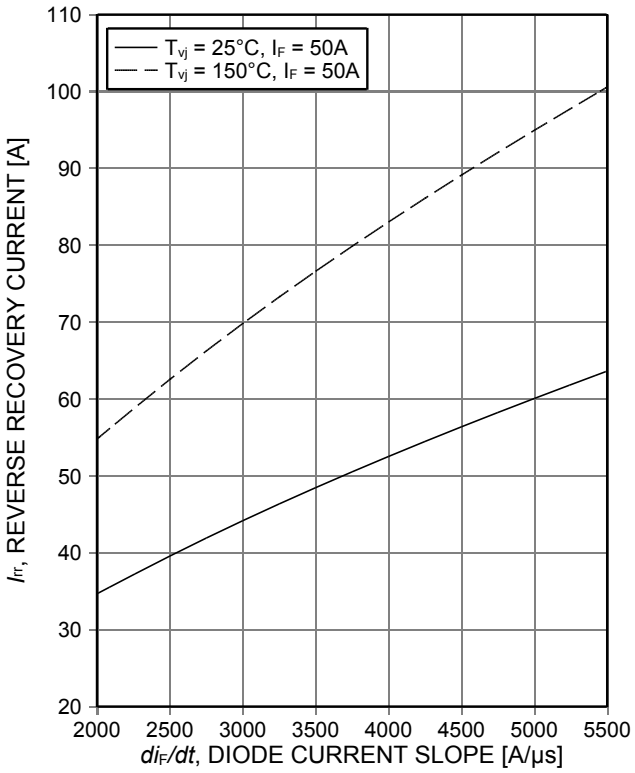


Figure 21. **Typical reverse recovery current as a function of diode current slope**
(V_R=400V)

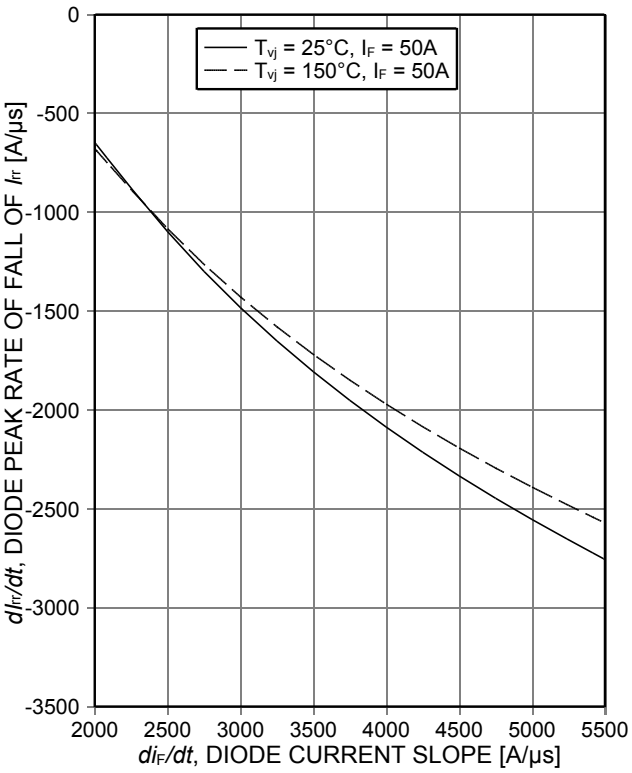


Figure 22. **Typical diode peak rate of fall of reverse recovery current as a function of diode current slope**
(V_R=400V)

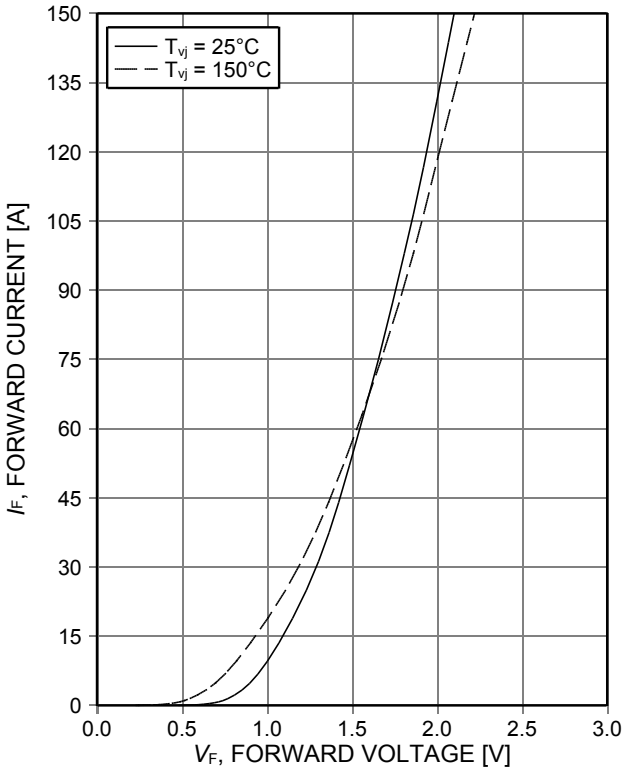


Figure 23. **Typical diode forward current as a function of forward voltage**

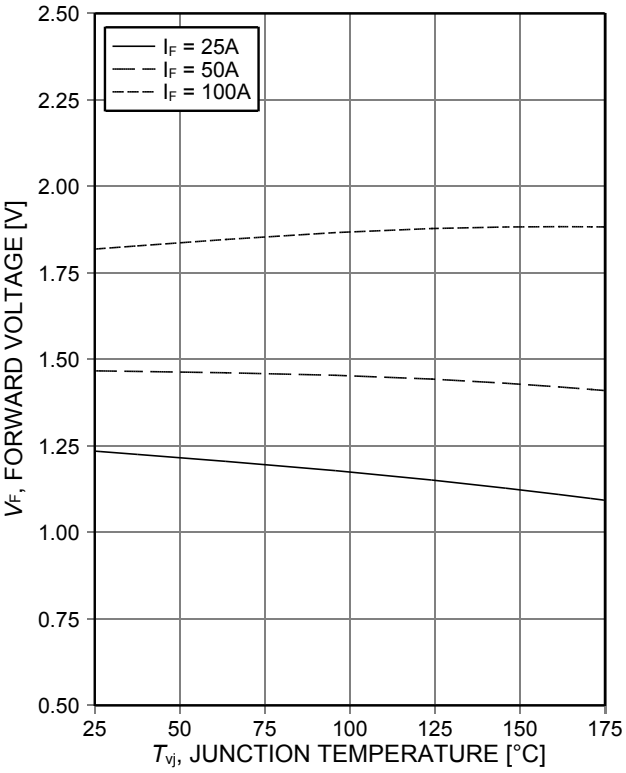
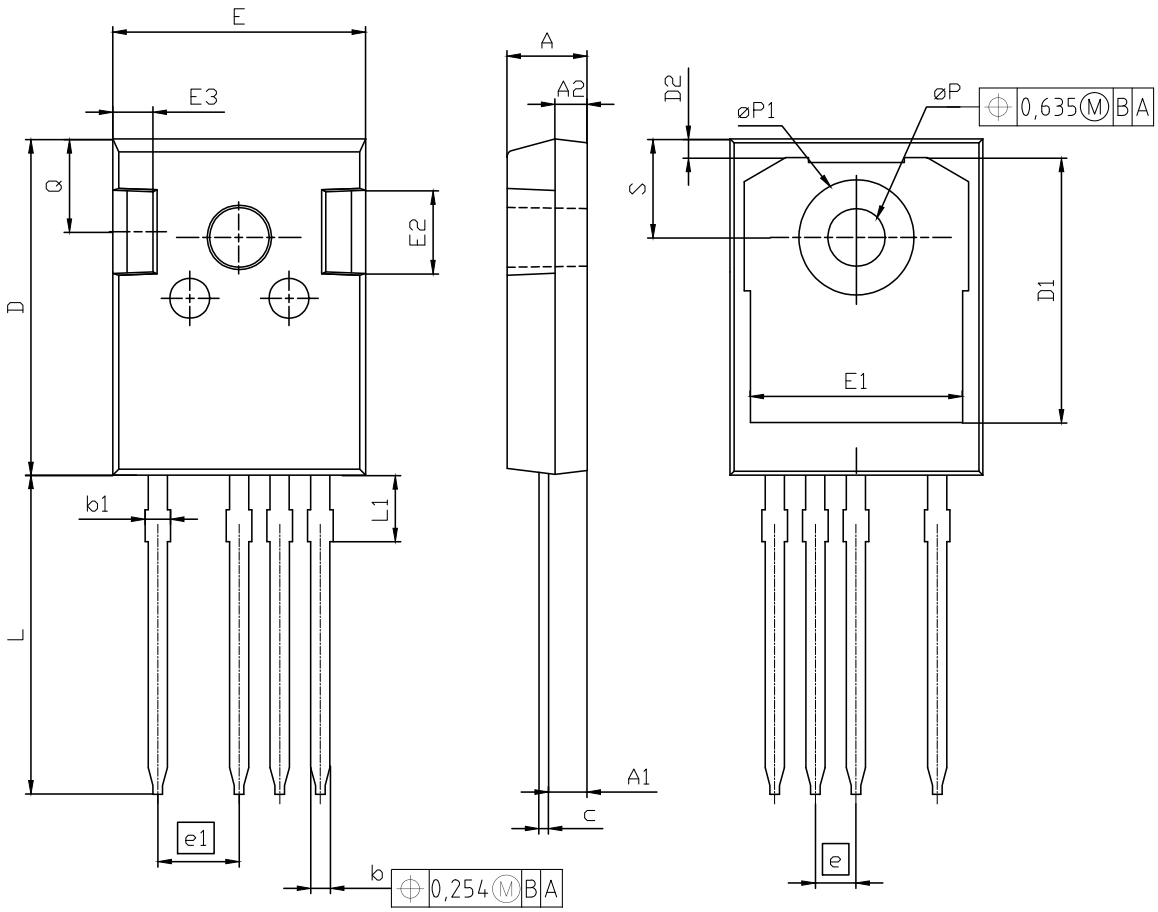


Figure 24. **Typical diode forward voltage as a function of junction temperature**

Package Drawing PG-TO247-4

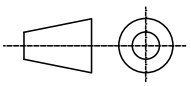


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.83	5.21	0.190	0.205
A1	2.29	2.54	0.090	0.100
A2	1.90	2.16	0.075	0.085
b	1.07	1.33	0.042	0.052
b1	1.10	1.70	0.043	0.067
c	0.50	0.70	0.020	0.028
D	20.80	21.10	0.819	0.831
D1	16.25	17.65	0.640	0.695
D2	0.95	1.35	0.037	0.053
E	15.70	16.13	0.618	0.635
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.00	2.60	0.039	0.102
e	2.54 (BSC)		0.100 (BSC)	
e1	5.08		0.200	
N	4		4	
L	19.72	20.32	0.776	0.800
L1	4.02	4.40	0.158	0.173
øP	3.50	3.70	0.138	0.146
øP1	7.00	7.40	0.276	0.291
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248

DOCUMENT NO.
Z8B00168124

SCALE
0 5 5 7.5mm

EUROPEAN PROJECTION



ISSUE DATE
29-01-2013

REVISION
1

Testing Conditions

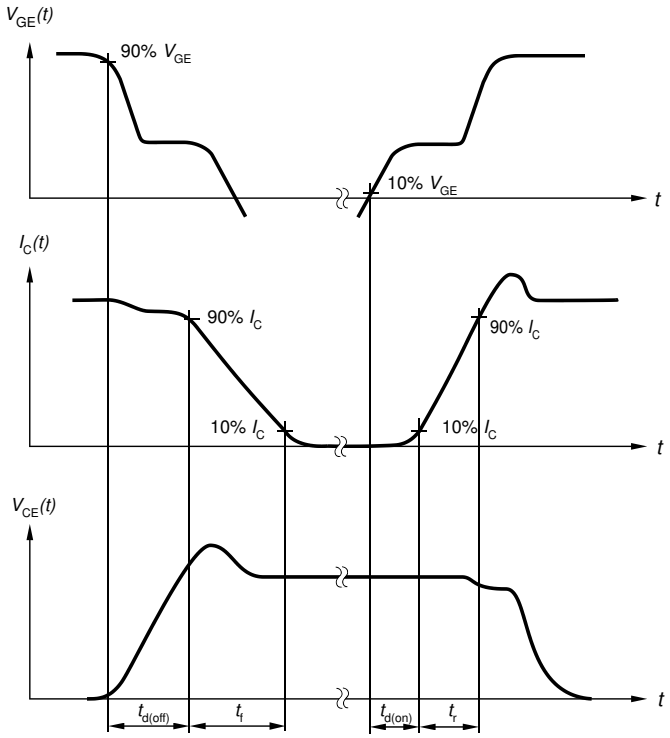


Figure A. **Definition of switching times**

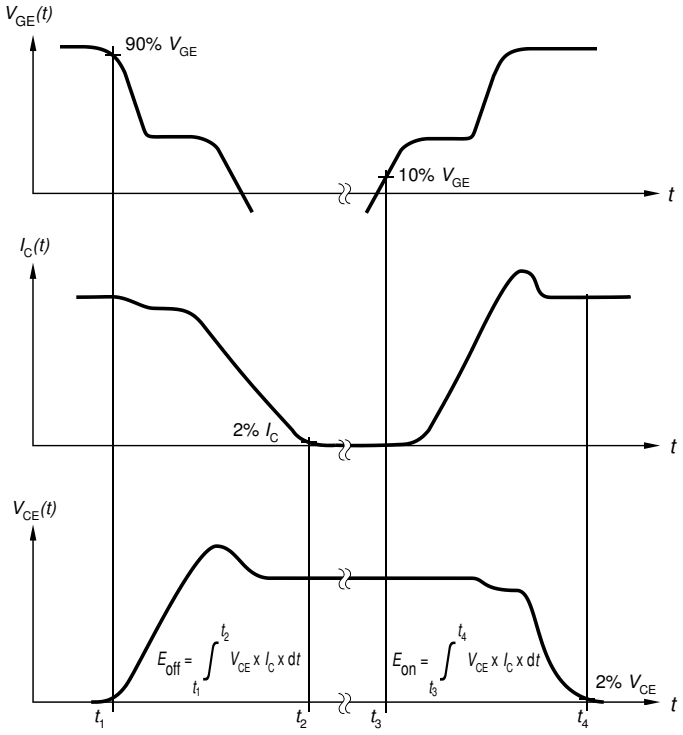


Figure B. **Definition of switching losses**

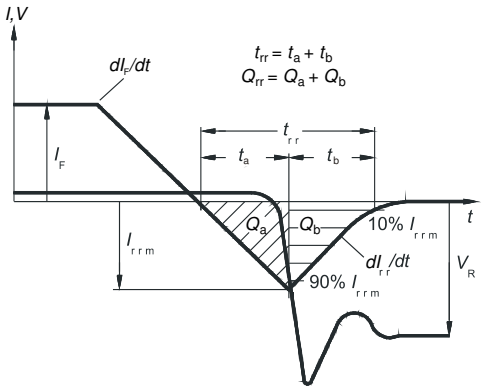


Figure C. **Definition of diode switching characteristics**

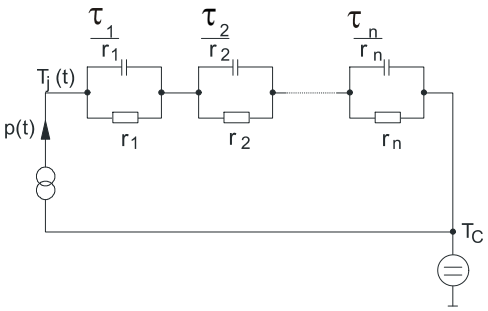


Figure D. **Thermal equivalent circuit**

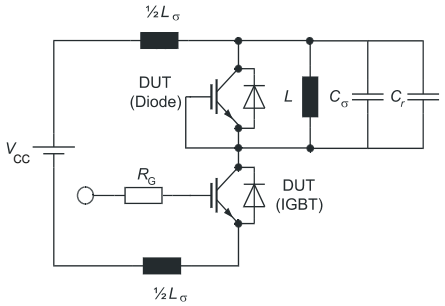


Figure E. **Dynamic test circuit**
Parasitic inductance L_σ,
parasitic capacitor C_σ,
relief capacitor C_r,
(only for ZVT switching)

Revision History

IKZ50N65ES5

Revision: 2017-04-26, Rev. 2.1

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.1	2017-04-26	Final data sheet

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